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Renesas Electronics website: http://www.renesas.com

April 1<sup>st</sup>, 2010 Renesas Electronics Corporation

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# MOS FIELD EFFECT TRANSISTOR NP109N04PUJ

# SWITCHING N-CHANNEL POWER MOS FET

#### **DESCRIPTION**

The NP109N04PUJ is N-channel MOS Field Effect Transistor designed for high current switching applications.

#### ORDERING INFORMATION

PART NUMBER	LEAD PLATING	PACKING	PACKAGE		
NP109N04PUJ-E1B-AY Note	_	Tape 1000 p/reel	TO-263 (MP-25ZP) typ. 1.5 g		
NP109N04PUJ-E2B-AY Note	Pure Sn (Tin)				

**Note** Pb-free (This product does not contain Pb in external electrode.)

#### **FEATURES**

• Super low on-state resistance  $R_{DS(on)} = 2.3 \text{ m}\Omega \text{ MAX.} \text{ (V}_{GS} = 10 \text{ V}, I_D = 55 \text{ A}\text{)}$ 

(TO-263)

Low input capacitance
 C<sub>iss</sub> = 6900 pF TYP.

• Designed for automotive application and AEC-Q101 qualified

#### ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

Drain to Source Voltage (V <sub>GS</sub> = 0 V)	VDSS	40	V
Gate to Source Voltage (VDS = 0 V)	Vgss	±20	V
Drain Current (DC) (Tc = 25°C)	I <sub>D(DC)</sub>	±110	Α
Drain Current (pulse) Note1	I <sub>D(pulse)</sub>	±440	Α
Total Power Dissipation (Tc = 25°C)	P <sub>T1</sub>	220	W
Total Power Dissipation (T <sub>A</sub> = 25°C)	P <sub>T2</sub>	1.8	W
Channel Temperature	Tch	175	°C
Storage Temperature	Tstg	-55 to +175	°C
Single Avalanche Energy Note2	Eas	360	mJ
Repetitive Avalanche Current Note3	Iar	60	Α
Repetitive Avalanche Energy Note3	Ear	360	mJ



**Notes 1.** PW  $\leq$  10  $\mu$ s, Duty Cycle  $\leq$  1%

**2.** Starting T<sub>ch</sub> = 25°C, V<sub>DD</sub> = 20 V, R<sub>G</sub> = 25  $\Omega$ , V<sub>GS</sub> = 20  $\rightarrow$  0 V, L = 100  $\mu$ H

3. Tch  $\leq$  150°C, Rg = 25  $\Omega$ 

#### THERMAL RESISTANCE

Channel to Case Thermal Resistance	Rth(ch-C)	0.68	°C/W
Channel to Ambient Thermal Resistance	Rth(ch-A)	83.3	°C/W

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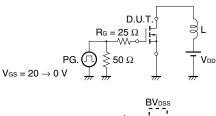
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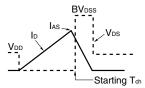
#### **ELECTRICAL CHARACTERISTICS (TA = 25°C)**

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> = 40 V, V <sub>GS</sub> = 0 V			1	μΑ
Gate Leakage Current	Igss	V <sub>GS</sub> = ±20 V, V <sub>DS</sub> = 0 V			±100	nA
Gate to Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2.0	3.0	4.0	V
Forward Transfer Admittance Note	yfs	V <sub>DS</sub> = 5 V, I <sub>D</sub> = 55 A	45	102		S
Drain to Source On-state Resistance Note	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 55 A		1.7	2.3	mΩ
Input Capacitance	Ciss	V <sub>DS</sub> = 25 V,		6900	10350	pF
Output Capacitance	Coss	V <sub>GS</sub> = 0 V,		930	1400	pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		360	650	pF
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 20 V, I <sub>D</sub> = 55 A,		40	90	ns
Rise Time	tr	V <sub>GS</sub> = 10 V,		20	50	ns
Turn-off Delay Time	t <sub>d(off)</sub>	$R_G = 0 \Omega$		85	170	ns
Fall Time	tf			15	40	ns
Total Gate Charge	Q <sub>G</sub>	V <sub>DD</sub> = 32 V,		115	180	nC
Gate to Source Charge	Q <sub>GS</sub>	V <sub>GS</sub> = 10 V,		26		nC
Gate to Drain Charge	Q <sub>GD</sub>	I <sub>D</sub> = 110 A		38		nC
Body Diode Forward Voltage Note	V <sub>F(S-D)</sub>	I <sub>F</sub> = 110 A, V <sub>GS</sub> = 0 V		0.9	1.5	V
Reverse Recovery Time	trr	I <sub>F</sub> = 110 A, V <sub>GS</sub> = 0 V,		57		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/ <i>μ</i> s		105		nC

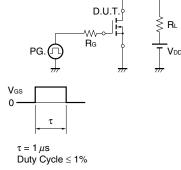
Note Pulsed test

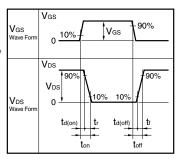
#### TEST CIRCUIT 1 AVALANCHE CAPABILITY





#### TEST CIRCUIT 2 SWITCHING TIME



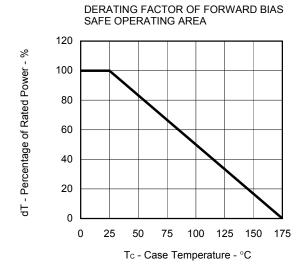


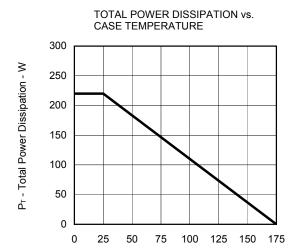
#### **TEST CIRCUIT 3 GATE CHARGE**

$$\begin{array}{c|c} D.U.T. \\ \hline I_G = 2 \text{ mA} \\ \hline \hline \\ V_{DD} \\ \hline \end{array}$$

2

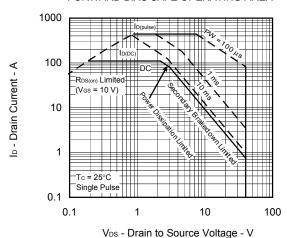
#### TYPICAL CHARACTERISTICS (TA = 25°C)



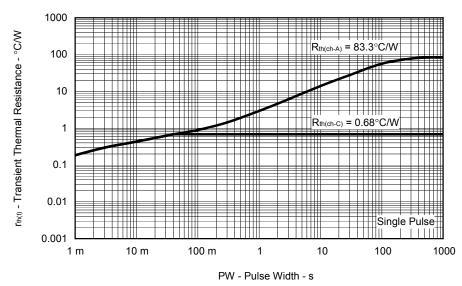


Tc - Case Temperature - °C

#### FORWARD BIAS SAFE OPERATING AREA



#### TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



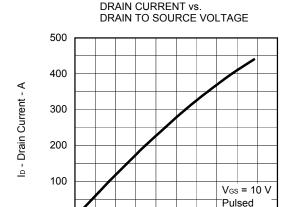
Data Sheet D19728EJ1V0DS 3

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0.2

CHANNEL TEMPERATURE



GATE TO SOURCE THRESHOLD VOLTAGE vs.

VDS - Drain to Source Voltage - V

0.6

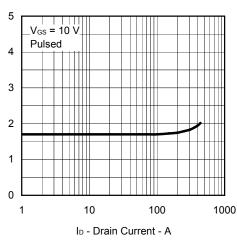
8.0

1

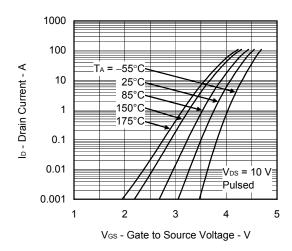
0.4

DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT

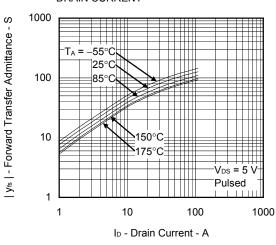
Tch - Channel Temperature - °C



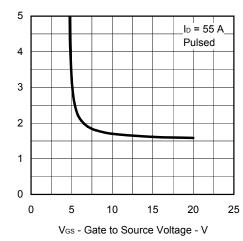
#### FORWARD TRANSFER CHARACTERISTICS



FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE

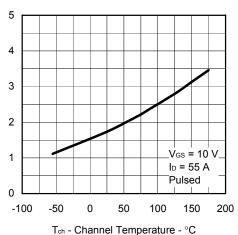


 $\mathsf{R}_{\mathsf{DS}(\mathsf{on})}$  - Drain to Source On-state Resistance -  $m\Omega$ 

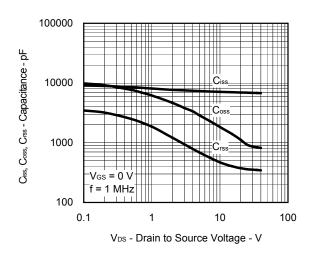
R<sub>DS(on)</sub> - Drain to Source On-state Resistance - mΩ

R<sub>DS(m)</sub> - Drain to Source On-state Resistance - mΩ

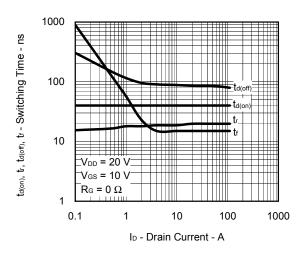
# DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



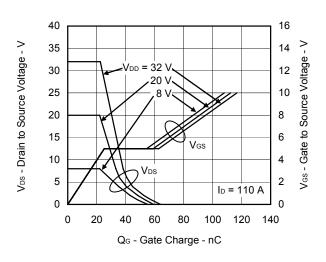
#### CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



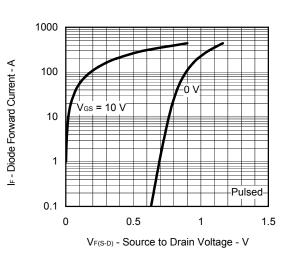
#### SWITCHING CHARACTERISTICS



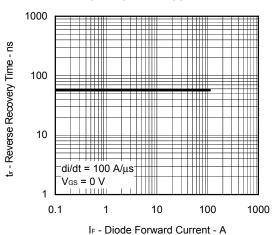
#### DYNAMIC INPUT/OUTPUT CHARACTERISTICS



#### SOURCE TO DRAIN DIODE FORWARD VOLTAGE

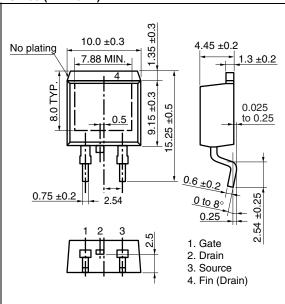


### REVERSE RECOVERY TIME vs. DIODE FORWARD CURRENT

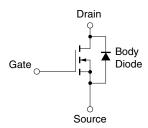


#### PACKAGE DRAWING (Unit: mm)

#### TO-263 (MP-25ZP)



#### **EQUIVALENT CIRCUIT**

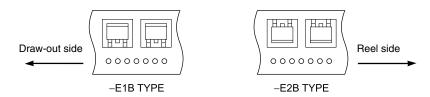


**Remark** Strong electric field, when exposed to this device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred.

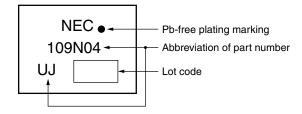
6

#### TAPE INFORMATION

There are two types (-E1B, -E2B) of taping depending on the direction of the device.



#### MARKING INFORMATION



#### RECOMMENDED SOLDERING CONDITIONS

The NP109N04PUJ should be soldered and mounted under the following recommended conditions.

For soldering methods and conditions other than those recommended below, please contact an NEC Electronics sales representative.

For technical information, see the following website.

Semiconductor Device Mount Manual (http://www.necel.com/pkg/en/mount/index.html)

Soldering Method	Soldering Conditions	Recommended Condition Symbol
Infrared reflow	Maximum temperature (Package's surface temperature): 260°C or below	IR60-00-3
	Time at maximum temperature: 10 seconds or less	
	Time of temperature higher than 220°C: 60 seconds or less	
	Preheating time at 160 to 180°C: 60 to 120 seconds	
	Maximum number of reflow processes: 3 times	
	Maximum chlorine content of rosin flux (percentage mass): 0.2% or less	
Partial heating	Maximum temperature (Pin temperature): 350°C or below	P350
	Time (per side of the device): 3 seconds or less	
	Maximum chlorine content of rosin flux: 0.2% (wt.) or less	

Caution Do not use different soldering methods together (except for partial heating).

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